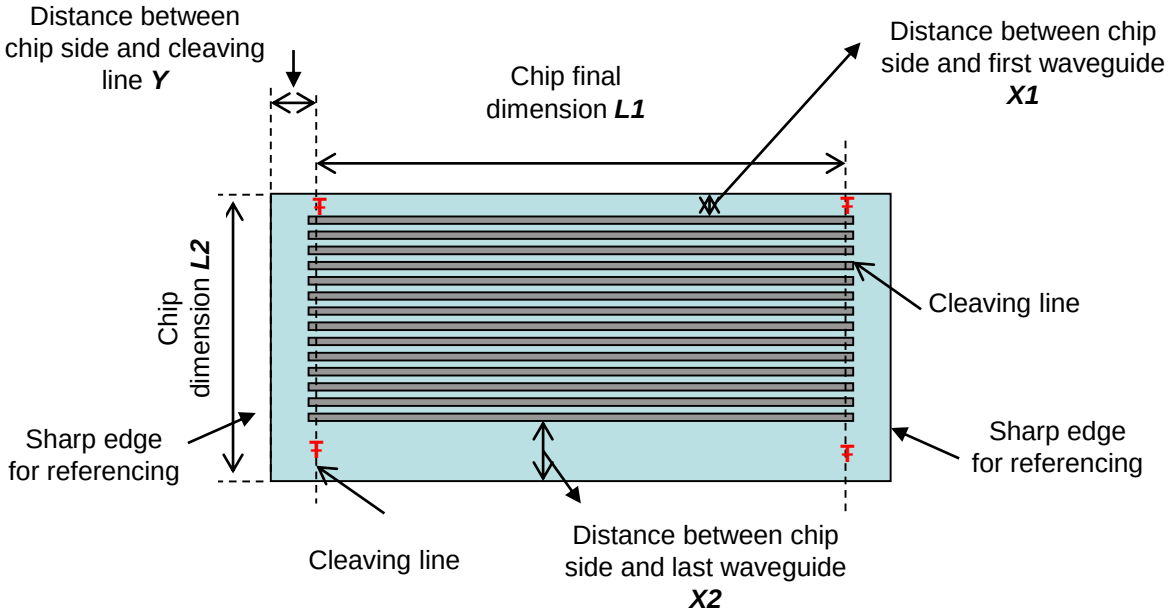
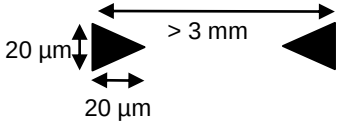
Guidelines for Laser Assisted Cleaving

(parallel cleaves)



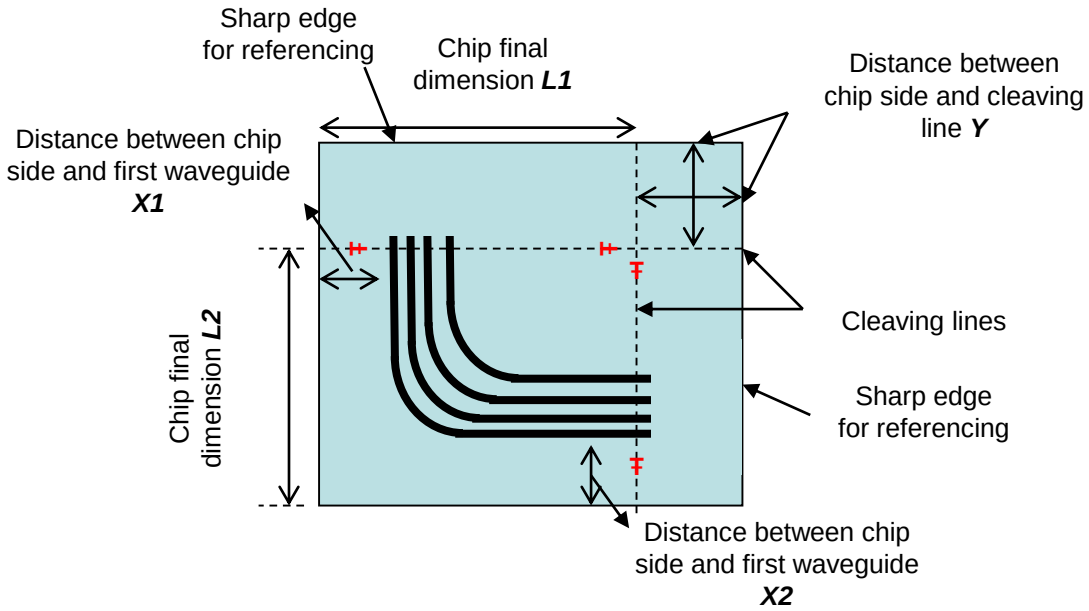
- ***L1***: Chip final dimension (along waveguides) shall be ***L1*** > 4 mm
- ***L2***: Chip final dimension (across waveguides) shall be 4 mm < ***L2*** < 10 mm
- ***Y***: Distance from chip side to cleaving line shall be 1 mm < ***Y*** < 2 mm
- ***X1* and *X2***: Distances between chip side and waveguide shall be > 0.7 mm for one and shall be > 0.2 mm for the other.
- The sides along the cleaving lines shall be sharp enough for referencing. (Predicing can be done to meet those requirements.)
- At least two marks along each cleaving line spaced by at least 3 mm are required for alignment.(∓)
- Alignment marks should clearly indicate the line to be cleaved with an accuracy of ± 2 µm. For example,



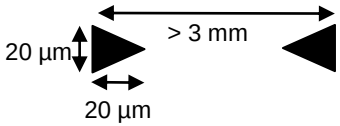
Accuracy on the position of the cleaved line with respect to the waveguide is ± 15 µm. Thus, permitted zone for cleaving should be at least 30 µm wide.

Guidelines for Laser Assisted Cleaving

(perpendicular cleaves)



- ***L1 and L2***:Chip final dimension shall be > 4 mm and < 10 mm
- ***Y***: Distance from chip side to cleaving line shall be 1 mm < ***Y*** < 2 mm
- ***X1* and *X2***: Distances between chip side and waveguide shall be > 0.7 mm.
- The sides along the cleaving lines shall be sharp enough for referencing. (Predicing can be done to meet those requirements.)
- At least two marks along each cleaving line spaced by at least 3 mm are required for alignment.(∓)
- Alignment marks should clearly indicate the line to be cleaved with an accuracy of ± 2 µm. For example,



Accuracy on the position of the cleaved line with respect to the waveguide is ± 15 µm. Thus, permitted zone for cleaving should be at least 30 µm wide.